

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Huicai Zhong</td><td>05/19/2011</td></tr><tr><td>Qingqing Zhong</td><td>05/19/2011</td></tr><tr><td>Chao Zhao</td><td>05/19/2011</td></tr></tbody></table>	Name	Execution Date	Huicai Zhong	05/19/2011	Qingqing Zhong	05/19/2011	Chao Zhao	05/19/2011	
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Huicai Zhong	05/19/2011								
Qingqing Zhong	05/19/2011								
Chao Zhao	05/19/2011								
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PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13201125</td></tr></tbody></table>	Property Type	Number	Application Number:	13201125					
Property Type	Number								
Application Number:	13201125								
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PATENT  
REEL: 026736 FRAME: 0938

# ASSIGNMENT

Attorney Docket No

First Named Inventor : Huicai ZHONG

Title : METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER

WHEREAS, We, Huicai ZHONG; Qingqing LIANG; Chao ZHAO have invented certain new and useful improvements as described in an application entitled METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER for Letters Patent of the United States, the application having been executed on even date herewith, and/or being identifiable in the United States Patent and Trademark Office by Application No. \_\_\_\_\_, filed \_\_\_\_\_; and

WHEREAS, INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES, a corporation organized and existing under the laws of P.R. China, and having offices at No.3 Beitucheng West Road, Chaoyang District, Beijing 100029, China ("Assignee") is desirous of acquiring the entire right, title and interest in and to the invention, the application, and any and all Letters Patent or similar legal protection, foreign or domestic, to be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, I transfer to Assignees, their successors and assigns, my entire right, title and interest in and to the invention, the above-identified application, corresponding domestic and foreign applications, all Letters Patent or similar legal protection issuing thereon, and all rights and benefits under any applicable treaty or convention; and I authorize the Commissioner of Patents and Trademarks of the United States or foreign equivalent thereof to issue the Letters Patent or similar legal protection to the Assignees.

I authorize the Assignees, their successors and assigns, to insert in this instrument the filing date and application number of the application when ascertained.

I authorize the Assignees, their successors and assigns, or anyone it may properly designate, to apply for Letters Patent or similar legal protection, in their own names if desired, in any and all foreign countries.

I represent to the Assignees, their successors and assigns, that I have not and shall not execute any writing or do any act whatsoever conflicting with this Assignment. I, my executors or administrators, will at any time upon request, without additional consideration, but at the expense of the Assignees, their successors and assigns, execute such additional writings and do such additional acts as the Assignees, their successors and assigns, may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the Letters Patent or similar legal protection on the invention in any and all countries.

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